

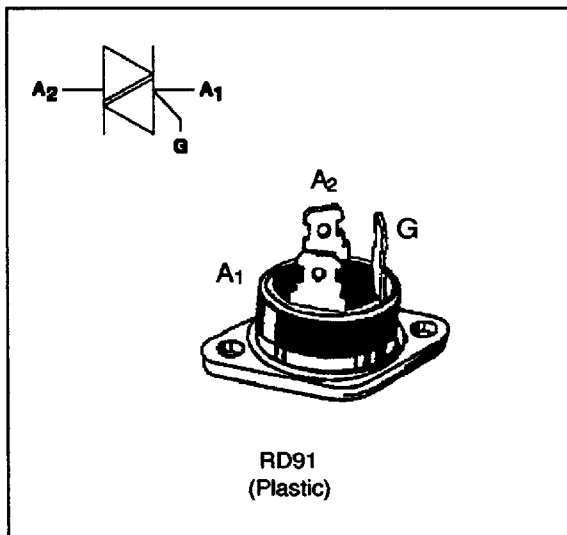
STANDARD TRIACS

FEATURES

- HIGH SURGE CURRENT CAPABILITY
- COMMUTATION : $(dV/dt)_c > 10V/\mu s$
- BTA Family :
INSULATING VOLTAGE = 2500V(RMS)
(UL RECOGNIZED : E81734)

DESCRIPTION

The BTA40 A/B triac family are high performance glass passivated PNP devices. These parts are suitable for general purpose applications where high surge current capability is required. Application such as phase control and static switching on inductive or resistive load.



ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$I_T(RMS)$	RMS on-state current (360° conduction angle)	$T_c = 75^\circ C$	40	A
I_{TSM}	Non repetitive surge peak on-state current (T_j initial = $25^\circ C$)	$t_p = 8.3$ ms	315	A
		$t_p = 10$ ms	300	
I_2t	I_2t value	$t_p = 10$ ms	450	A ² s
di/dt	Critical rate of rise of on-state current Gate supply : $I_G = 500mA$ $di_G/dt = 1A/\mu s$	Repetitive $F = 50$ Hz	10	A/ μs
		Non Repetitive	50	
T_{stg} T_j	Storage and operating junction temperature range		- 40 to + 150 - 40 to + 125	$^\circ C$ $^\circ C$
T_l	Maximum lead temperature for soldering during 10 s at 4.5 mm from case		260	$^\circ C$

Symbol	Parameter	BTA40-... A/B				Unit
		400	600	700	800	
V_{DRM} V_{RRM}	Repetitive peak off-state voltage $T_j = 125^\circ C$	400	600	700	800	V

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
Rth (j-c) DC	Junction to case for DC	1.2	°C/W
Rth (j-c) AC	Junction to case for 360° conduction angle (F = 50 Hz)	0.9	°C/W

GATE CHARACTERISTICS (maximum values)

PG (AV) = 1W PGM = 40W (tp = 20 μs) IGM = 8A (tp = 20 μs) VGM = 16V (tp = 20 μs).

ELECTRICAL CHARACTERISTICS

Symbol	Test Conditions		Quadrant		Suffix		Unit
					A	B	
IGT	VD=12V (DC) RL=33Ω	Tj=25°C	I-II-III	MAX	100	50	mA
			IV	MAX	150	100	
VGT	VD=12V (DC) RL=33Ω	Tj=25°C	I-II-III-IV	MAX	1.5		V
VGD	VD=VDRM RL=3.3kΩ	Tj=125°C	I-II-III-IV	MIN	0.2		V
tgt	VD=VDRM IG = 500mA dIG/dt = 3A/μs	Tj=25°C	I-II-III-IV	TYP	2.5		μs
IL	IG=1.2 IGT	Tj=25°C	I-III-IV	TYP	70	60	mA
			II		200	180	
IH *	IT= 500mA gate open	Tj=25°C		MAX	100	80	mA
VTM *	ITM= 60A tp= 380μs	Tj=25°C		MAX	1.8		V
IDRM IRRM	VDRM Rated VRRM Rated	Tj=25°C		MAX	0.01		mA
		Tj=125°C		MAX	6		
dV/dt *	Linear slope up to VD=67%VDRM gate open	Tj=125°C		MIN	250		V/μs
(dV/dt)c *	(dI/dt)c = 18A/ms	Tj=125°C		MIN	10		V/μs

* For either polarity of electrode A2 voltage with reference to electrode A1.

ORDERING INFORMATION

Package	$I_T(\text{RMS})$	$V_{\text{DRM}} / V_{\text{RRM}}$	Sensitivity Specification	
	A	V	A	B
BTA (Insulated)	40	400	X	X
		600	X	X
		700	X	X
		800	X	X

Fig.1 : Maximum RMS power dissipation versus RMS on-state current ($F=50\text{Hz}$).
(Curves are cut off by $(di/dt)_c$ limitation)

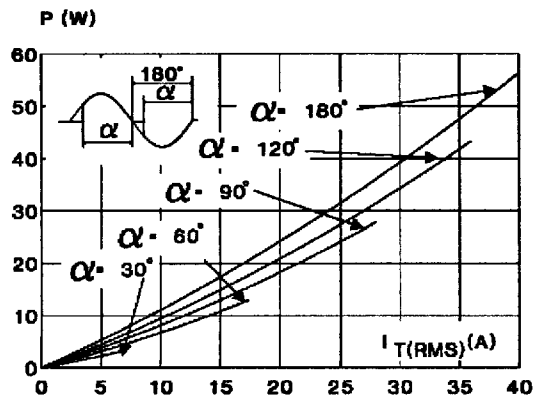


Fig.3 : RMS on-state current versus case temperature.

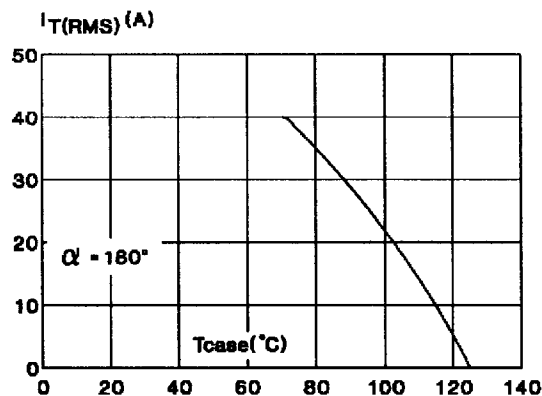


Fig.2 : Correlation between maximum RMS power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

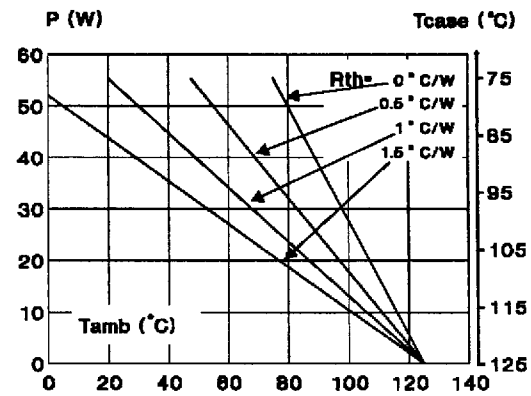


Fig.4 : relative variation of thermal impedance junction to case versus pulse duration.

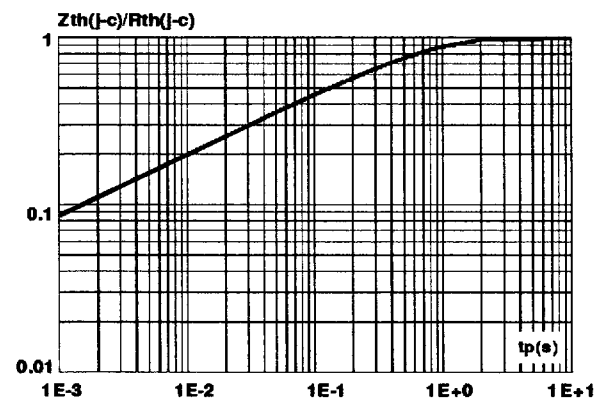


Fig.5 : Relative variation of gate trigger current and holding current versus junction temperature.

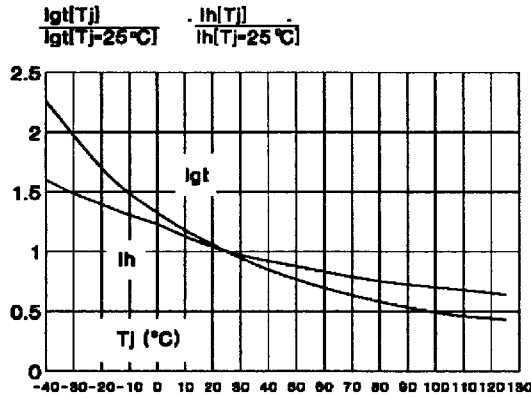


Fig.6 : Non Repetitive surge peak on-state current versus number of cycles.

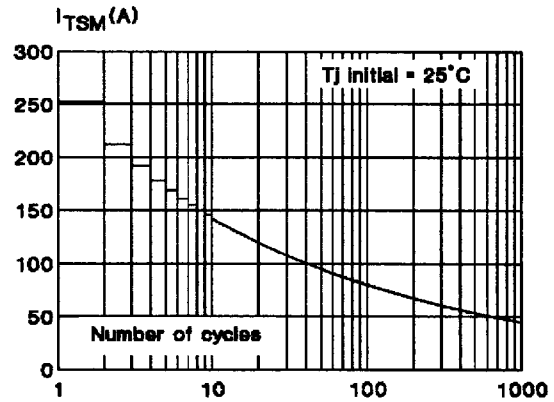


Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10\text{ms}$, and corresponding value of I^2t .

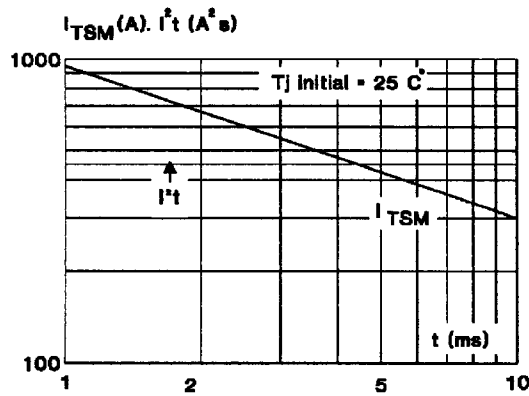
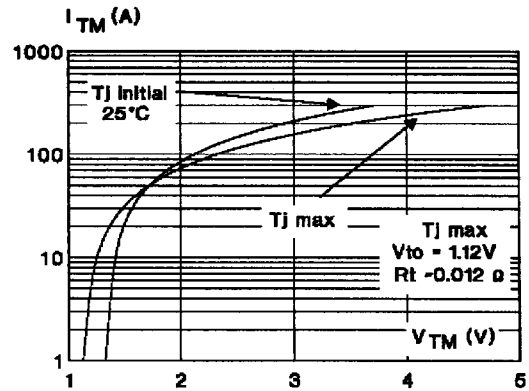
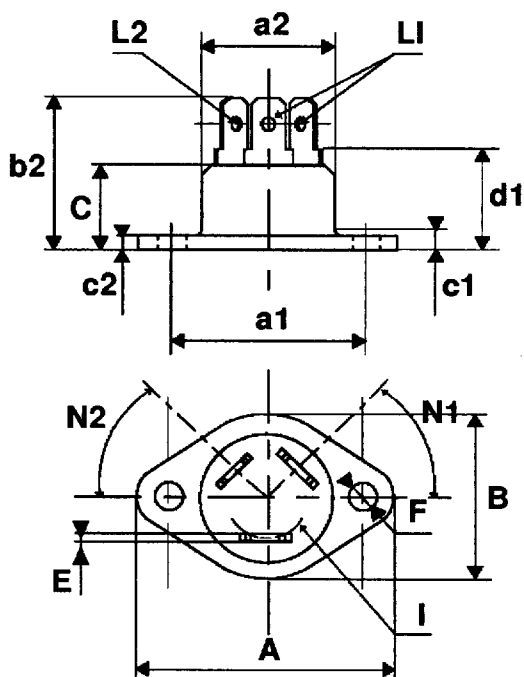


Fig.8 : On-state characteristics (maximum values).



PACKAGE MECHANICAL DATA

RD91 Plastic



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		40.00		1.575
a1	29.90	30.30	1.177	1.193
a2		22.00		0.867
B		27.00		1.063
b1	13.50	16.50	0.531	0.650
b2		24.00		0.945
C		14.00		0.551
c1		3.50		0.138
c2	1.95	3.00	0.077	0.118
E	0.70	0.90	0.027	0.035
F	4.00	4.50	0.157	0.177
I	11.20	13.60	0.441	0.535
L1	3.10	3.50	0.122	0.138
L2	1.70	1.90	0.067	0.075
N1	33°	43°	33°	43°
N2	28°	38°	28°	38°

Marking : type number
Weight : 20 g

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